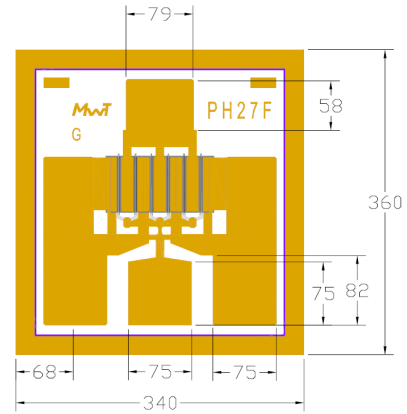


Features:

- 25 dBm of Power at 18 GHz
- 14 dB Small Signal Gain at 18 GHz
- 45% PAE at 18 GHz
- 0.25 x 400 Micron Refractory Metal/Gold Gate
- Excellent for Medium Power, Gain, and High Power Added Efficiency
- Ideal for Commercial, Military, Hi-Rel Space Applications



Chip Dimensions: 340 x 360 microns
Chip Thickness: 100 microns

Description:

The MwT-PH27F is a AlGaAs/InGaAs pHEMT (Pseudomorphic-High-Electron-Mobility-Transistor) device whose nominal 0.25 micron gate length and 400 micron gate width make it ideally suited for applications requiring high-gain and medium power up to 26 GHz frequency range. The device is equally effective for either wideband (e.g. 6 to 18 GHz) or narrow-band applications. The chip is produced using reliable metal systems and passivated to insure excellent reliability.

Electrical Specifications: at $T_a = 25\text{ }^\circ\text{C}$

PARAMETERS & CONDITIONS	SYMBOL	FREQ	UNITS	MIN	TYP
Output Power at 1dB Compression $V_{ds}=9.0\text{V}$ $I_{ds}=0.7 \times I_{DSS}$	P1dB	18 GHz	dBm		22.5
Saturated Power $V_{ds}=9.0\text{V}$ $I_{ds}=0.7 \times I_{DSS}$	P _{sat}	18 GHz	dBm		25.0
Output Third Order Intercept Point $V_{ds}=9.0\text{V}$ $I_{ds}=0.7 \times I_{DSS}$	OIP3	18 GHz	dBm		31.0
Small Signal Gain $V_{ds}=9.0\text{V}$ $I_{ds}=0.7 \times I_{DSS}$	SSG	18 GHz	dB		16.0
Power Added Efficiency at P1dB $V_{ds}=9.0\text{V}$ $I_{ds}=0.7 \times I_{DSS}$	PAE	18 GHz	%		45

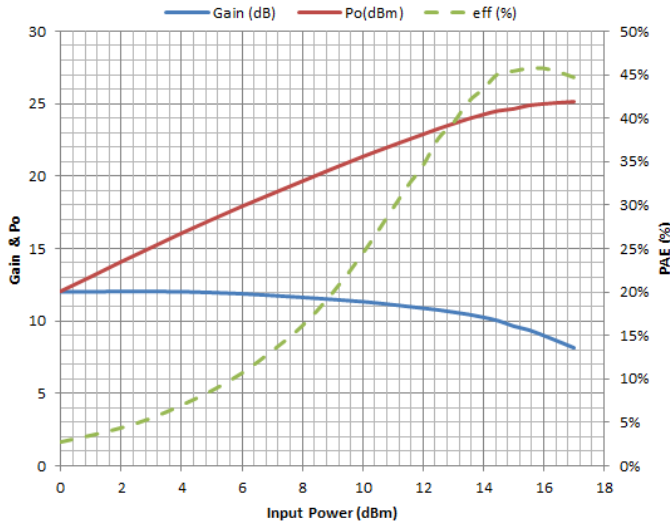
Note: I_{ds} should be between 40% and 80% of I_{DSS} . Currently, our data shows I_{ds} at 70% of I_{DSS} . Low I_{ds} will improve efficiency, but high I_{ds} will make P_{sat} and IP3 better.

DC Specifications: at $T_a = 25\text{ }^\circ\text{C}$

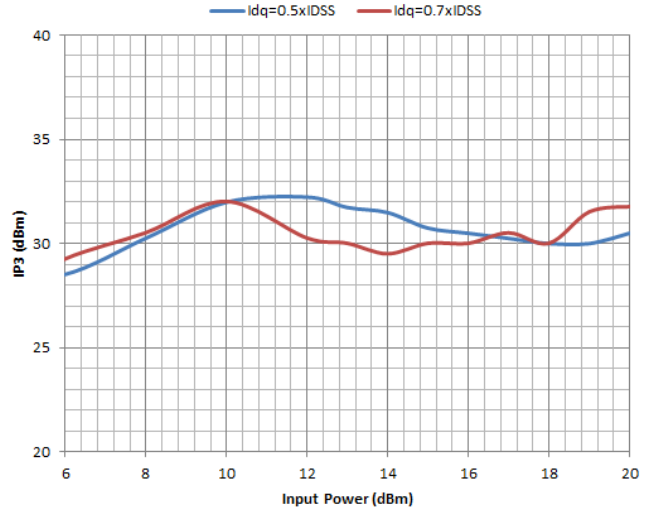
PARAMETERS & CONDITIONS	SYMBOL	UNITS	MIN	TYP	MAX
Saturated Drain Current $V_{ds}=3.0\text{V}$ $V_{gs}=0.0\text{V}$	I_{DSS}	mA	90		120
Transconductance $V_{ds}=2.5\text{V}$ $V_{gs}=0.0\text{V}$	G _m	mS		140	
Pinch-off Voltage $V_{ds}=3.0\text{V}$ $I_{ds}=1.0\text{mA}$	V_p	V		-0.8	-1.0
Gate-to-Source Breakdown Voltage $I_{gs}=-0.3\text{mA}$	BVGSO	V		-18.0	
Gate-to-Drain Breakdown Voltage $I_{gd}=-0.3\text{mA}$	BVGDO	V		-18.0	
Chip Thermal Resistance	R _{th}	C/W		95	225*
	Chip & 71 pkg 70 & 73 pkg				

* Overall R_{th} depends on case mounting

MwT-PH27F, Po, Gain & PAE vs Pin
Vds=8V; Idq=0.7xIdss



MwT-PH27F, OIP3 vs Po/tone
with different Idq

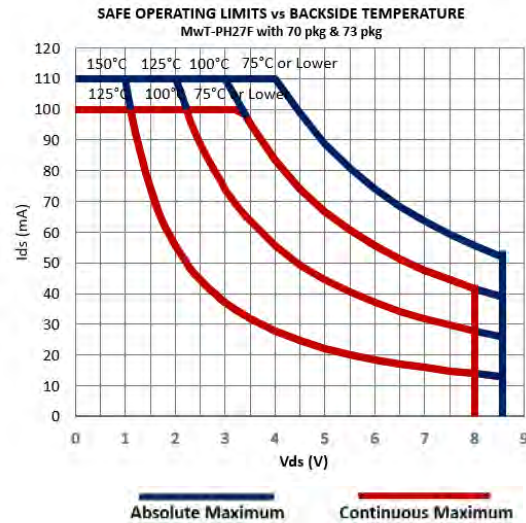
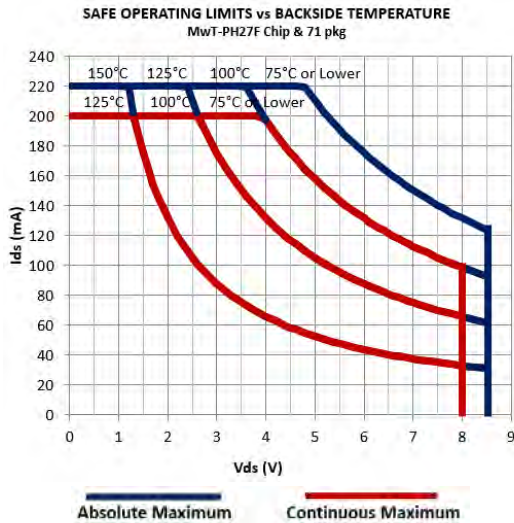
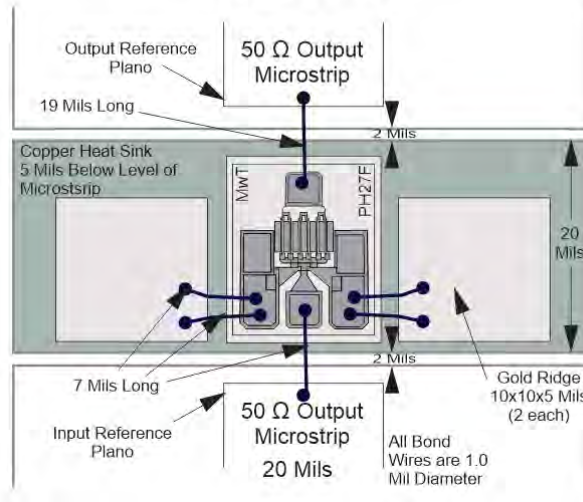


MwT-PH27F, Load Pull Data, Vdq=8V; Idq=0.7xIdss

Freq (GHz)	Zs		ZL		Psat dBm
	Mag	phase	mag	phase	
2	0.84	50.00	0.16	22.56	25.8
4	0.77	90.00	0.17	33.56	25.9
6	0.76	112.00	0.19	46.65	25.8
8	0.79	129.00	0.28	65.03	25.6
10	0.80	137.00	0.28	70.74	25.7
12	0.82	149.00	0.35	78.36	25.5
14	0.86	151.00	0.38	83.73	25.3
16	0.83	160.00	0.38	84.90	25.3
18	0.85	164.00	0.43	97.06	25.3

The load pull data is based on nonlinear model provided by the foundry that processes the device.

MwT-PH27F DUAL BIAS



Absolute Maximum Rating

Symbol	Parameter	Units	Cont Max1	Absolute Max2
VDS	Drain to Source Volt.	V	8.0	8.5
Tch	Channel Temperature	°C	+150	+175
Tst	Storage Temperature	°C	-65 to +150	+175
Pin	RF Input Power	mW	130	200

Notes:

1. Exceeding any one of these limits in continuous operation may reduce the mean-time-to-failure below the design goal.
2. Exceeding any one of these limits may cause permanent damage.